



International Conference on Bond Graph Modeling and Simulation
January 19-23 2003 • Airport Marriott Plaza Hotel • Orlando, Florida U.S.A.

ANNOUNCEMENT AND CALL FOR PAPERS

The Society for Modeling and Simulation International (SCS) presents:

2003 INTERNATIONAL CONFERENCE ON BOND GRAPH MODELING AND SIMULATION
January 19-23 2003 at the Airport Marriott Hotel
Orlando, Florida U.S.A.

Part of the 2003 SCS Western Multiconference on Computer Simulation

The 2003 International Conference on Bond Graph Modeling and Simulation brings together research paper presentations, panel sessions, tutorials, workshops, seminars, industrial applications, and software demonstrations that use Bond Graph modeling methods. There will be also featured plenary speakers and some special invited presentations.

This conference will focus on Bond Graph modeling techniques for dynamic systems. Theoretical principles for electrical, mechanical, hydraulic, pneumatic, and control system applications will be presented. Leading industrial users of the method in automotive, aircraft, fluid power, kinematics, multibody systems, and social and biological systems have been invited. Research papers are welcome in the following categories of presentation:

SESSIONS

- | | |
|------------------------------------|---|
| . Tutorials | . Control Systems |
| . Panel Discussions | . Bond Graphs and Block Diagrams |
| . Software and Tools | . Biological and Medical Systems |
| . Bond Graph Theory | . Thermal and Chemical Systems |
| . Mechanical Systems and Robotics. | . Biomechanics and Prosthetics |
| . Electrical and Power Systems | . Computer Graphics and Bond Graph Modeling |
| . Fluid Power | . Social and Economic Systems |
| . Qualitative Modeling | . Industrial Applications |
| . Mechatronics Systems | . Large, Nonlinear Models |

DEADLINES:

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|---------------------|---|
| . April 30, 2002 | Short Abstracts due (two copies). |
| . May 15, 2002 | Notification of abstract acceptance to authors. |
| . July 1, 2002 | Full papers due for review (five copies). |
| . September 1, 2002 | Notification of paper acceptance to authors. |
| . October 1, 2002 | Camera Ready Copies due. |

Abstracts and full papers can be submitted alternatively to the General Chair or the Program Chair. In addition to regular papers about 12 pages (double spaced), the program committee may accept additional papers, either as short papers (about 6 pages double-spaced), or proposals for tutorials. Please add a cover letter stating your name, affiliation, mail address, telephone number, FAX number, and e-mail address. The short abstracts will be reviewed by the two Chairs for general suitability to the conference. Three members of the International Program Committee will review each full paper.

GENERAL CHAIR

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If you are interested in receiving further announcements of this conference, please, return (preferably by e-mail) the card printed below to Prof. J. Granda at: grandajj@ecs.csus.edu or to Prof. F. Cellier at cellier@ece.arizona.edu

INTERNATIONAL CONFERENCE ON BOND GRAPH MODELING AND SIMULATION (ICBGM'2003):

Please, update your information and that of co-authors and others in the modeling and simulation field which you think may be interested.

Name _____

Affiliation _____ Phone: _____

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I intend to submit a paper to ICBGM'2003: YES [] NO []